

TLP2309

1. Applications

- Transistor Inverters
- Switching Power Supplies
- High-Speed Digital Interfacing

2. General

The Toshiba TLP2309 consists of a high-output GaAs infrared light-emitting diode coupled with a high-speed photo-diode-transistor chip. It is housed in the SO6 package.

The TLP2309 guarantees operation at up to 110°C and on supplies both 3.3 V and 5 V. Also, since the TLP2309 guarantees a creepage / clearance distance ≥ 5 mm and internal isolation thickness ≥ 0.4 mm, this product is in the reinforced insulation class according to international safety standards.

3. Features

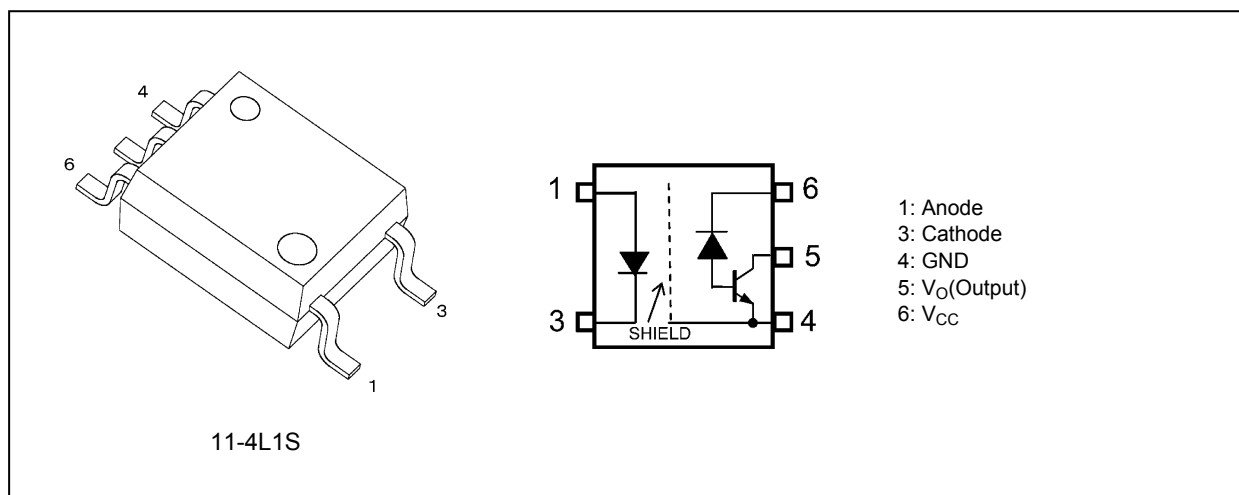
- (1) Inverter logic type (open collector output)
- (2) Package: SO6
- (3) Operating temperature: -40 to 110°C
- (4) Supply voltage: 3.3 V / 5 V
- (5) Data transfer rate: 1 Mbit/s (typ.) (NRZ)
- (6) Common-mode transient immunity: 15 kV/ μ s (min)
- (7) Isolation voltage: 3750 Vrms (min)
- (8) Safety standards

UL-approved: UL1577 File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A, File No.E67349

VDE-approved: Option (V4) EN60747-5-2

4. Packaging and Pin Configuration



5. Internal Circuit

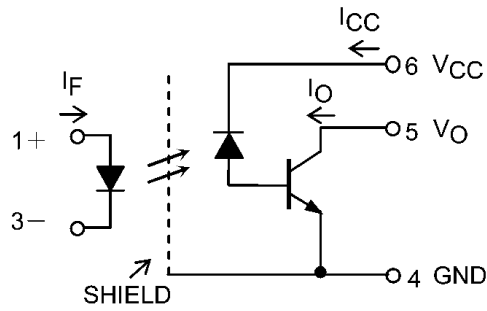


Fig. 5.1 Internal Circuit

6. Principle of Operation

6.1. Truth Table

Input	LED	Output
H	ON	L
L	OFF	H

6.2. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance distances	5.0	
Internal isolation thickness	0.4	

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25°C)

	Characteristics	Symbol	Note	Rating	Unit
LED	Input forward current	I _F		25	mA
	Input forward current derating (T _a ≥ 100°C)	ΔI _F /ΔT _a		-1.0	mA/°C
	Input forward current (pulsed)	I _{FP}	(Note 1)	50	mA
	Input forward current derating (pulsed) (T _a ≥ 100°C)	ΔI _{FP} /ΔT _a		-2.0	mA/°C
	Peak transient input forward current	I _{FPT}	(Note 2)	1	A
	Peak transient input forward current derating (T _a ≥ 85°C)	ΔI _{FPT} /ΔT _a		-25	mA/°C
	Input power dissipation	P _D		40	mW
	Input power dissipation derating (T _a ≥ 100°C)	ΔP _D /ΔT _a		-1.6	mW/°C
	Input reverse voltage	V _R		5	V
Detector	Output current	I _O		8	mA
	Peak output current	I _{OP}		16	
	Supply voltage	V _{CC}		-0.5 to 30	V
	Output voltage	V _O		-0.5 to 20	
	Output power dissipation	P _O		100	mW
	Output power dissipation derating (T _a ≥ 100°C)	ΔP _O /ΔT _a		-4.0	mW/°C
Common	Operating temperature	T _{opr}		-40 to 110	°C
	Storage temperature	T _{stg}		-55 to 125	
	Lead soldering temperature (10 s)	T _{sol}		260	
	Isolation voltage AC, 1 min, R.H. ≤ 60%	BV _S	(Note 3)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 1: Pulse width (PW) ≤ 1 ms, duty = 50%

Note 2: Pulse width (PW) ≤ 1 μs, 300 pps

Note 3: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

8. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
Input on-state current	I _{F(ON)}		10	—	20	mA
Input off-state voltage	V _{F(OFF)}		0	—	0.8	V
Supply voltage	V _{CC}		2.7	3.3 / 5	20	
Operating temperature	T _{opr}	(Note 1)	-40	—	110	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

Note: A ceramic capacitor (0.1 μF) should be connected between pin 6 and pin 4 to stabilize the operation. Otherwise, this photocoupler may not switch properly. The bypass capacitor should be placed within 1 cm of each pin.

Note 1: Denotes the operating range, not the recommended operating condition.

9. Electrical Characteristics (Note)
(Unless otherwise specified, $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input forward voltage	V_F	$I_F = 10\text{ mA}$	1.45	1.55	1.7	V
Input forward voltage temperature coefficient	$\Delta V_F/\Delta T_a$	$I_F = 10\text{ mA}$, $T_a = -40^\circ\text{C}$ to 110°C	—	-2.0	—	mV/°C
Input reverse current	I_R	$V_R = 5\text{ V}$	—	—	10	μA
Input capacitance	C_t	$V = 0\text{ V}$, $f = 1\text{ MHz}$	—	60	—	pF
High-level output current	I_{OH}	$I_F = 0\text{ mA}$, $V_O = 5.5\text{ V}$, $V_{CC} = 5.5\text{ V}$	—	3	500	μA
		$I_F = 0\text{ mA}$, $V_O = 20\text{ V}$, $V_{CC} = 30\text{ V}$	—	—	5	
		$I_F = 0\text{ mA}$, $V_O = 20\text{ V}$, $V_{CC} = 30\text{ V}$, $T_a = 110^\circ\text{C}$	—	—	50	
High-level supply current	I_{CCH}	$I_F = 0\text{ mA}$, $V_{CC} = 30\text{ V}$	—	0.01	1	
Current transfer ratio	I_O/I_F	$I_F = 10\text{ mA}$, $V_O = 0.4\text{ V}$, $V_{CC} = 3.3\text{ V}$	15	—	—	%
		$I_F = 16\text{ mA}$, $V_O = 0.4\text{ V}$, $V_{CC} = 4.5\text{ V}$	15	—	—	
Low-level output voltage	V_{OL}	$I_F = 16\text{ mA}$, $V_{CC} = 4.5\text{ V}$, $I_O = 2.4\text{ mA}$	—	—	0.4	V

Note: All typical values are at $T_a = 25^\circ\text{C}$.

10. Isolation Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Note	Test Conditions	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	$V_S = 0\text{ V}$, $f = 1\text{ MHz}$	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	$V_S = 500\text{ V}$, R.H. $\leq 60\%$	1×10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S		AC, 1 min	3750	—	—	Vrms
			AC, 1 s in oil	—	10000	—	
			DC, 1 min in oil	—	10000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

11. Switching Characteristics (Note)
(Unless otherwise specified, $T_a = -40$ to 110°C)

Characteristics	Symbol	Note	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Propagation delay time (H/L)	t_{pHL}		Fig. 12.1.1	$I_F = 0 \rightarrow 10\text{ mA}$, $R_L = 1.9\text{ k}\Omega$, $V_{CC} = 3.3\text{ V}$, $C_L = 15\text{ pF}$	—	—	1	μs
Propagation delay time (L/H)	t_{pLH}			$I_F = 10 \rightarrow 0\text{ mA}$, $R_L = 1.9\text{ k}\Omega$, $V_{CC} = 3.3\text{ V}$, $C_L = 15\text{ pF}$	—	—	1	
Propagation delay time (H/L)	t_{pHL}		Fig. 12.1.1	$I_F = 0 \rightarrow 16\text{ mA}$, $R_L = 1.9\text{ k}\Omega$, $V_{CC} = 5\text{ V}$, $C_L = 15\text{ pF}$	—	—	0.8	
Propagation delay time (L/H)	t_{pLH}			$I_F = 16 \rightarrow 0\text{ mA}$, $R_L = 1.9\text{ k}\Omega$, $V_{CC} = 5\text{ V}$, $C_L = 15\text{ pF}$	—	—	0.8	
Common-mode transient immunity at output high	CM_H	(Note 1)	Fig. 12.1.2	$I_F = 0\text{ mA}$, $V_{CC} = 3.3\text{ V} / 5\text{ V}$, $V_{CM} = 400\text{ V}_{p-p}$, $R_L = 4.1\text{ k}\Omega$, $T_a = 25^\circ\text{C}$	15	20	—	kV/ μs
Common-mode transient immunity at output low	CM_L	(Note 1)		$I_F = 10\text{ mA}$, $V_{CC} = 3.3\text{ V} / 5\text{ V}$, $V_{CM} = 400\text{ V}_{p-p}$, $R_L = 4.1\text{ k}\Omega$, $T_a = 25^\circ\text{C}$	-15	-20	—	

Note: All typical values are at $T_a = 25^\circ\text{C}$.

Note 1: CM_H is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state ($V_O > 2.0\text{ V}$).

CM_L is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state ($V_O < 0.8\text{ V}$).

12. Test Circuits and Characteristics Curves

12.1. Test Circuits

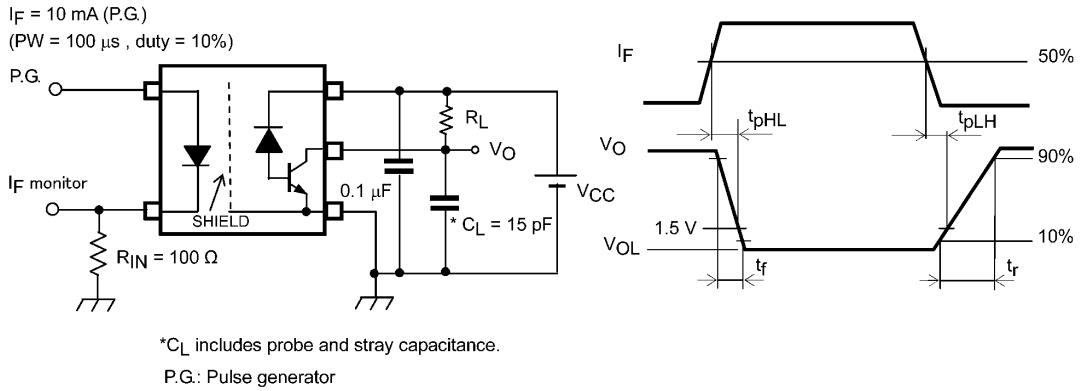


Fig. 12.1.1 Switching Time Test Circuit

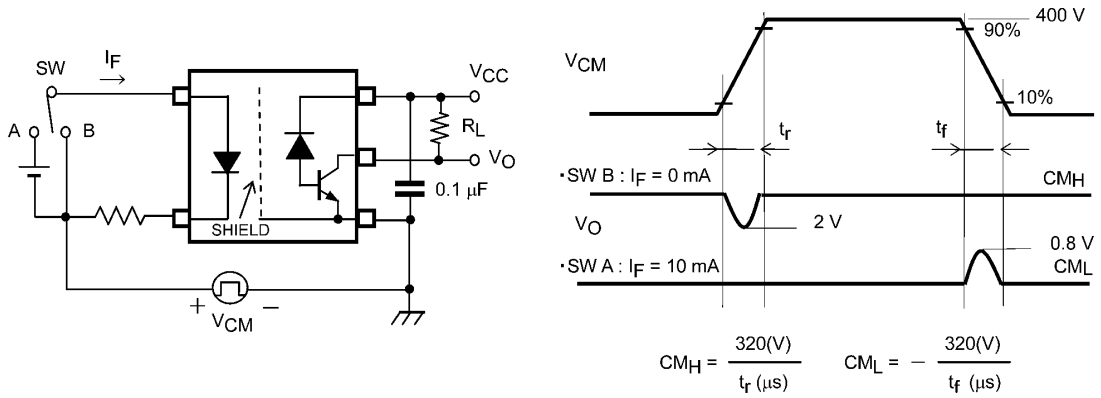


Fig. 12.1.2 Common-Mode Transient Immunity

12.2. Characteristics Curves (Note)

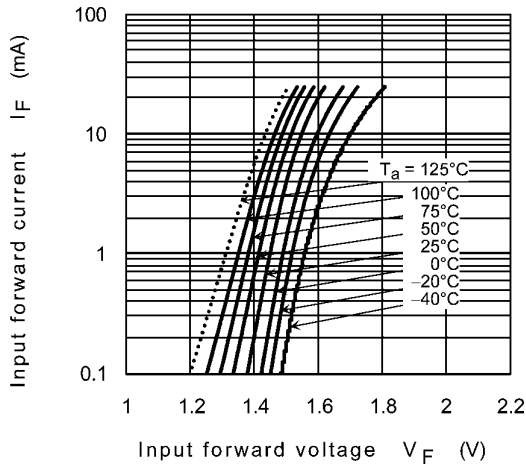


Fig. 12.2.1 $I_F - V_F$

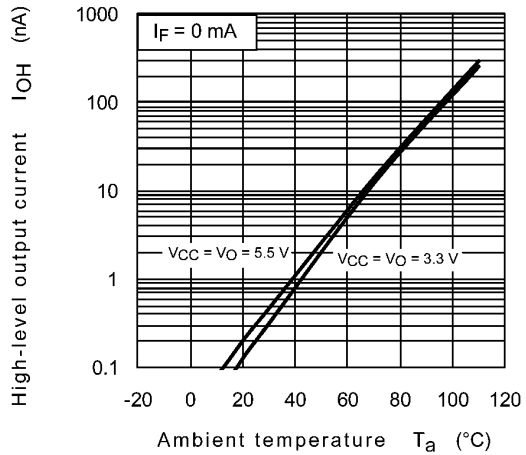


Fig. 12.2.2 $I_{OH} - T_a$

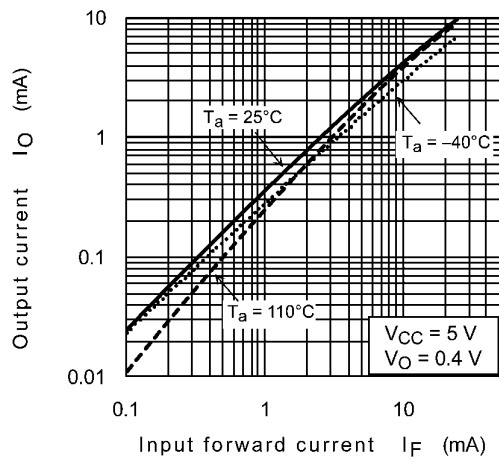


Fig. 12.2.3 $I_O - I_F$

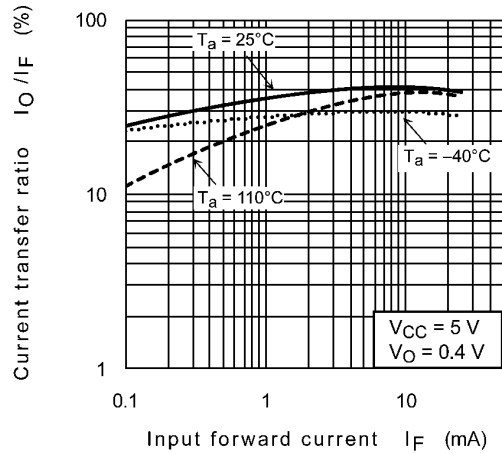


Fig. 12.2.4 $I_O/I_F - I_F$

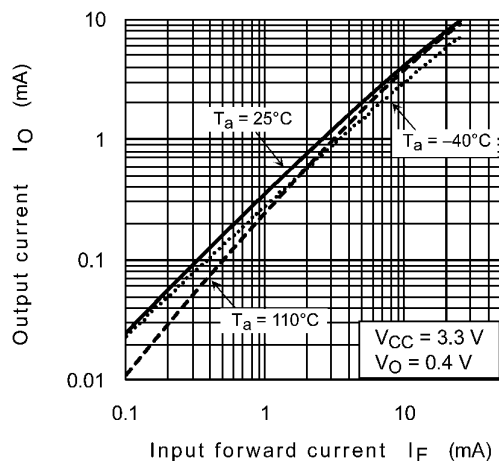


Fig. 12.2.5 $I_O - I_F$

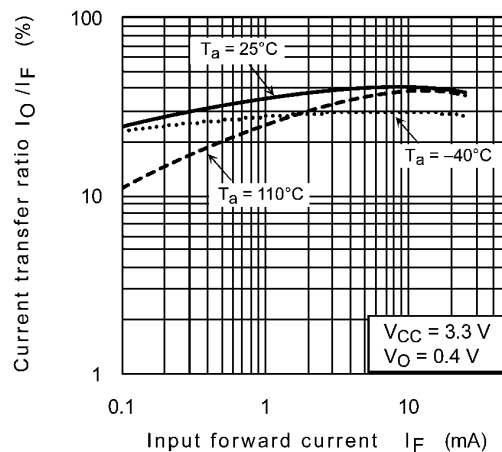


Fig. 12.2.6 $I_O/I_F - I_F$

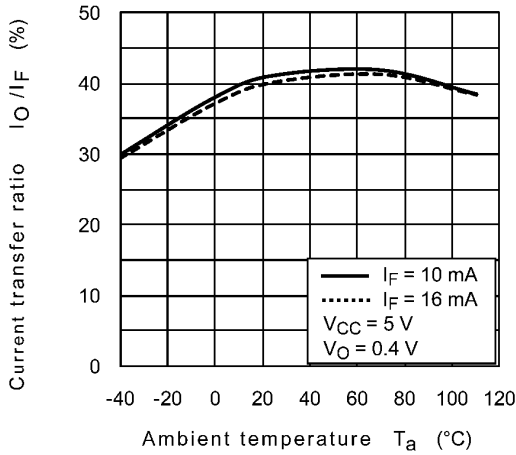


Fig. 12.2.7 $I_O/I_F - T_a$

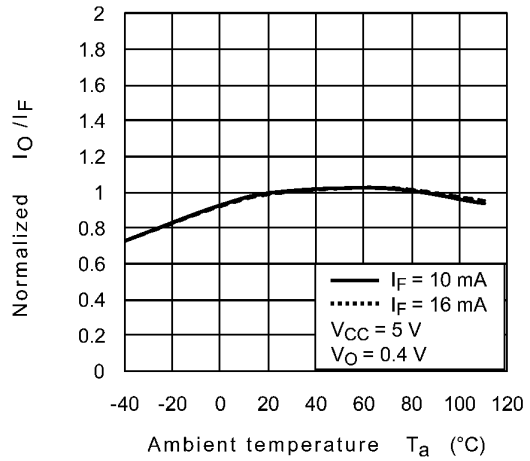


Fig. 12.2.8 $I_O/I_F - T_a$

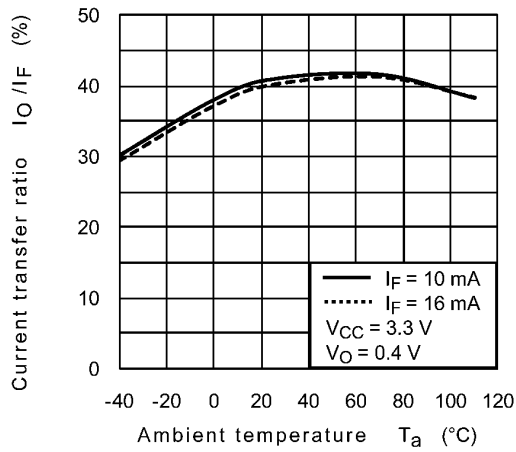


Fig. 12.2.9 $I_O/I_F - T_a$

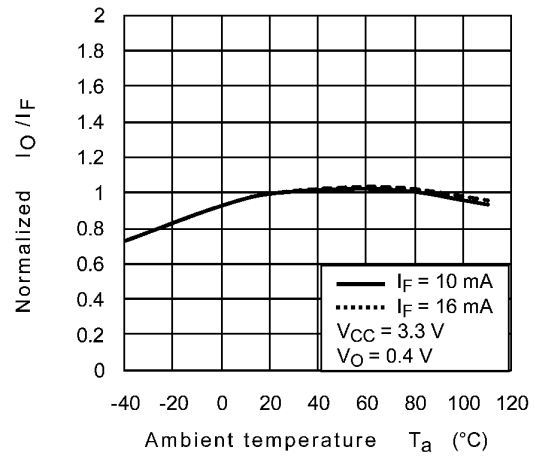


Fig. 12.2.10 $I_O/I_F - T_a$

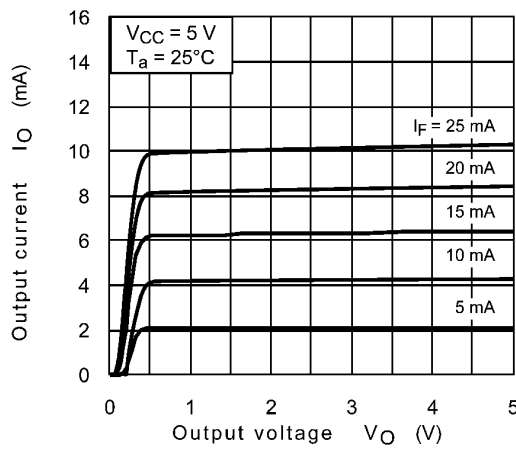


Fig. 12.2.11 $I_O - V_O$

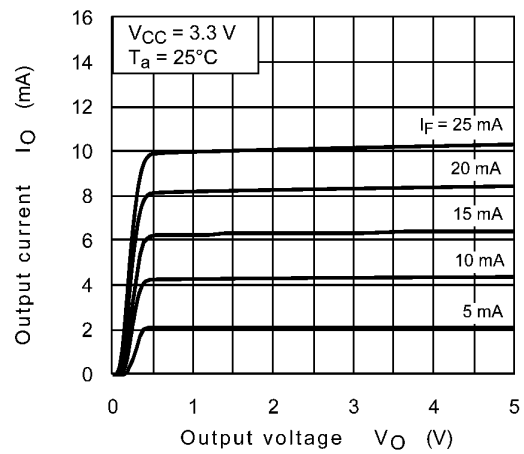


Fig. 12.2.12 $I_O - V_O$

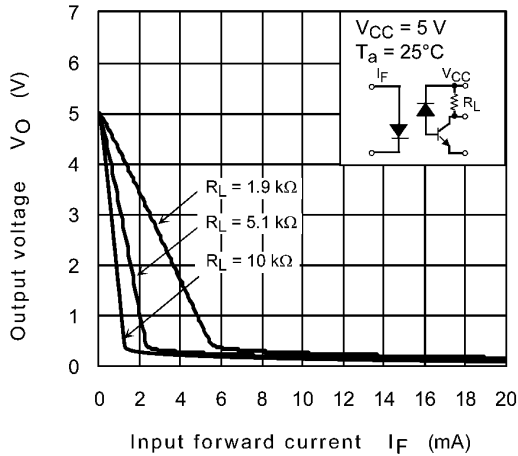


Fig. 12.2.13 $V_O - I_F$

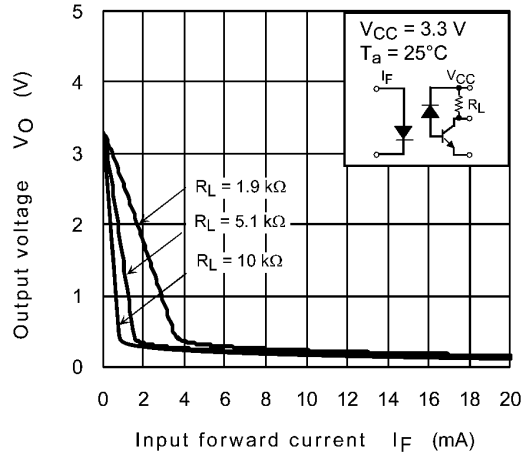


Fig. 12.2.14 $V_O - I_F$

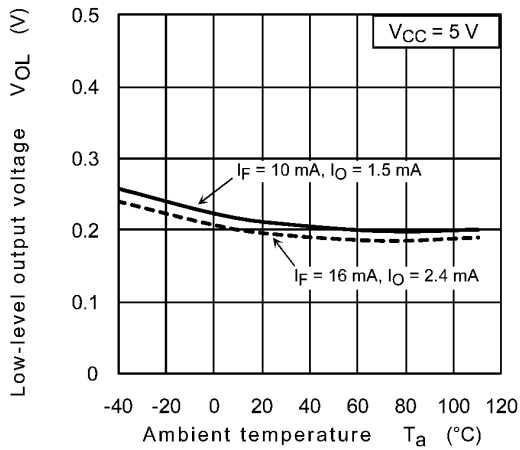


Fig. 12.2.15 $V_{OL} - T_a$

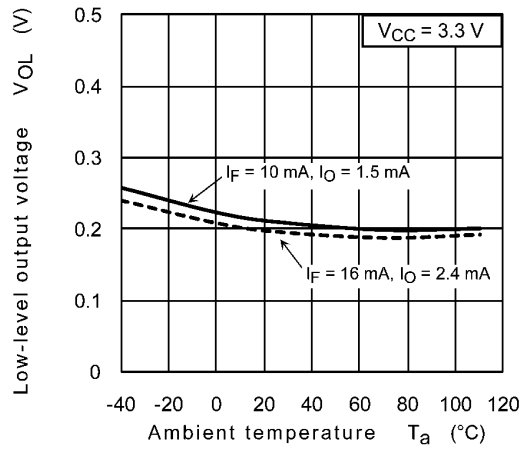


Fig. 12.2.16 $V_{OL} - T_a$

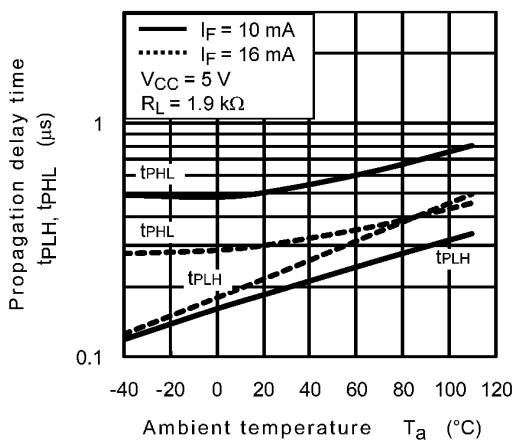


Fig. 12.2.17 $t_{PLH}, t_{PHL} - T_a$

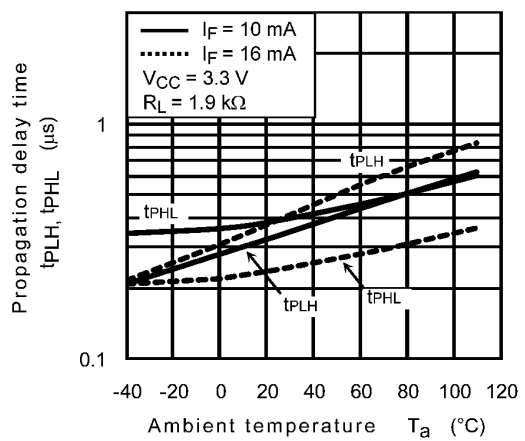


Fig. 12.2.18 $t_{PLH}, t_{PHL} - T_a$

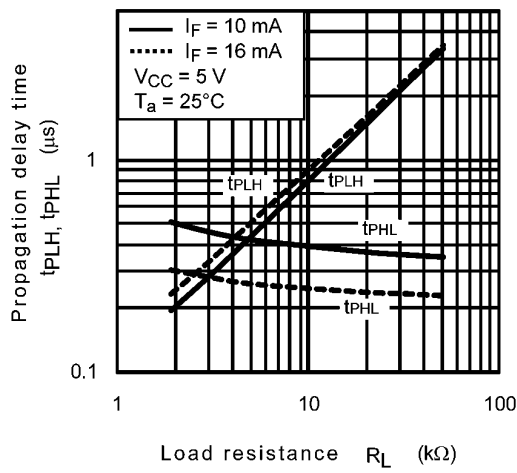


Fig. 12.2.19 t_{PLH} , $t_{PHL} - R_L$

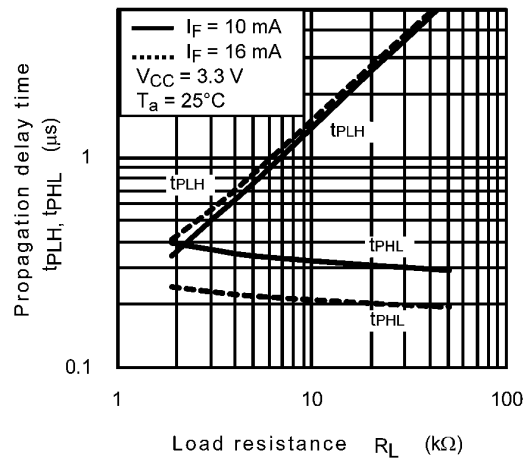


Fig. 12.2.20 t_{PLH} , $t_{PHL} - R_L$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow (See Fig. 13.1.1 and 13.1.2)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

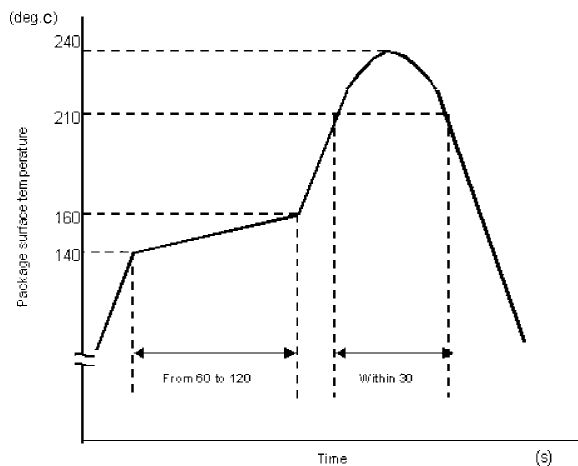


Fig. 13.1.1 An example of a temperature profile when Sn-Pb eutectic solder is used

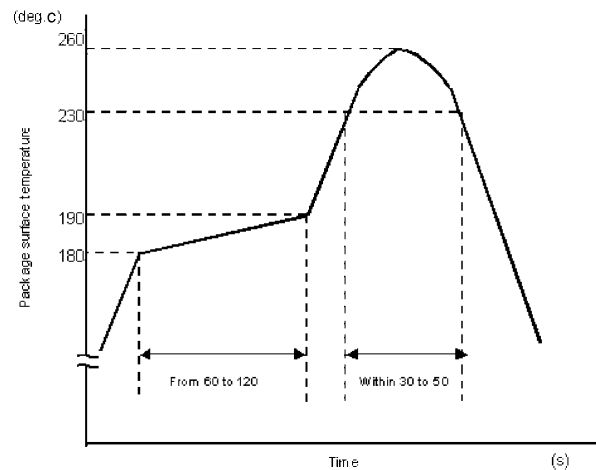


Fig. 13.1.2 An example of a temperature profile when lead(Pb)-free solder is used

- When using soldering flow (Applicable to both eutectic solder and Lead(Pb)-Free solder)
Apply preheating of 150°C for 60 to 120 seconds.
Mounting condition of 260°C within 10 seconds is recommended.
Flow soldering must be performed once.
- When using soldering Iron (Applicable to both eutectic solder and Lead(Pb)-Free solder)
Complete soldering within 10 seconds for lead temperature not exceeding 260°C or within 3 seconds not exceeding 350°C
Heating by soldering iron must be done only once per lead.

13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions for Reference Only

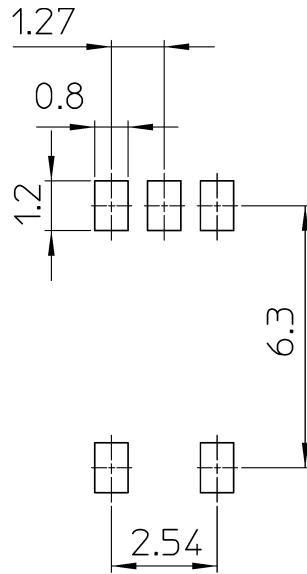


Fig. 14.1 Land Pattern Dimensions for Reference Only (unit: mm)

15. Marking

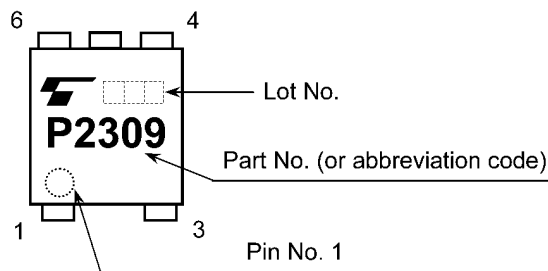
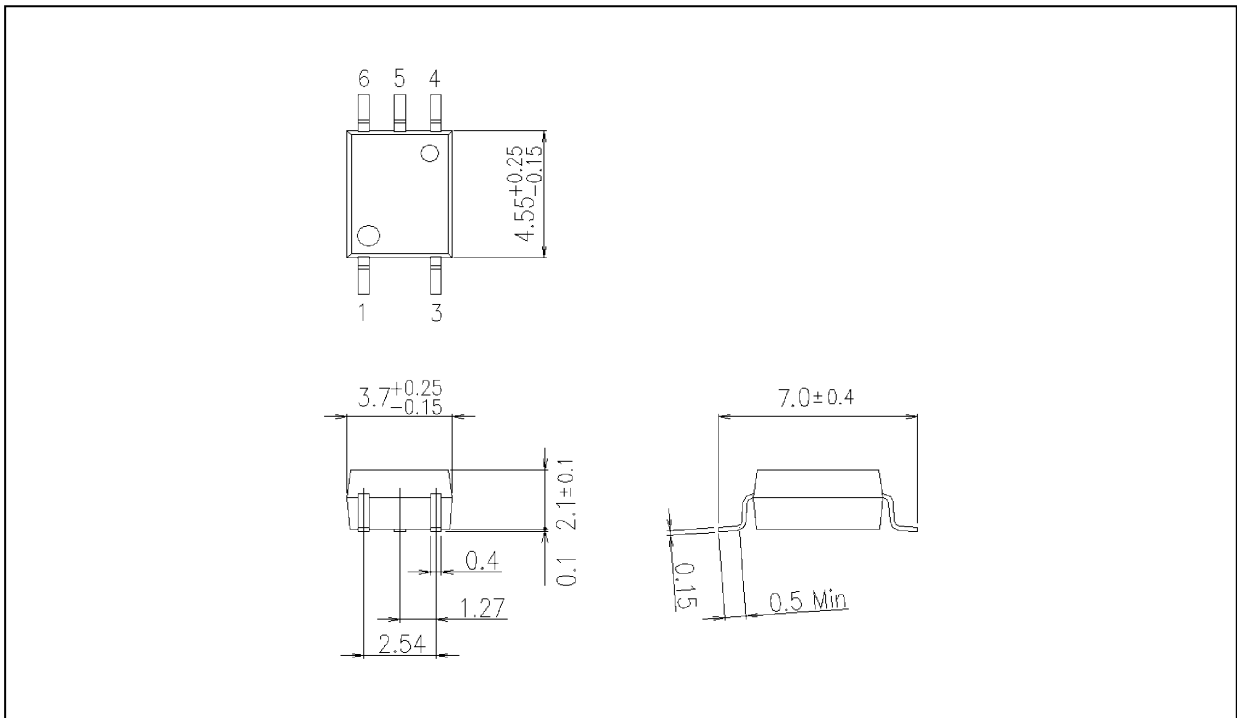


Fig. 15.1 Marking

Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

Package Name(s)
TOSHIBA: 11-4L1S

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